Materials Declaration

Package	SOIC_N
Body Size	150 mils
LeadCount	16
Option	Pb-free

Molding Compound

Substance	% of Compound	Weight (g)	PPM
Silica	86.20	8.21 E-02	527276
Epoxy resin	7.50	7.15 E-03	45877
Phenol Novolac	4.00	3.81 E-03	24468
Antimony Trioxide	1.50	1.43 E-03	9175
Brominated Resin	0.50	4.77 E-04	3058
Carbon Black	0.30	2.86 E-04	1835
Subtotal	100.0	9.53 E-02	611689

Leadframe

Substance	% of Leadframe	Weight (g)	PPM
Copper	97.5	5.06 E-02	324740
Iron	2.35	1.18 E-03	7585
Zinc	0.12	6.65 E-05	427
Phosphorus	0.03	1.26 E-05	81
Subtotal	100	5.19 E-02	332832

Internal Leadframe Plating

Substance	% of Plating	Weight (g)	PPM
Silver	100	5.24 E-04	3362

External Leadframe Plating

Substance	% of Plating	Weight (g)	PPM
Tin	100	2.92 E-03	18740

Bond Wires

Substance	% of Wire	Weight (g)	PPM
Gold	99.99	5.10 E-04	3273

Chip

Substance	% of Chip	Weight (g)	PPM
Doped Silicon	100	3.57 E-03	22914

Die Attach

Substance	% of Die Attach	Weight (g)	PPM
Silver	80	8.96 E-04	5751
Epoxy Resin	15	1.68 E-04	1078
Curing agent & hardener	5	5.60 E-05	359
Subtotal	100	1.12 E-03	7189

Package Totals

Weight (g)	PPM
1.56 E-01	1000000

Molding Compound

Substance	PPM	Method
Lead	Not Detected	Draft IEC 62321. ICP-OES.
Cadmium	Not Detected	Draft IEC 62321. ICP-OES.
Mercury	Not Detected	Draft IEC 62321. ICP-OES.
Chromium+6	Not Detected	Draft IEC 62321. UV-VIS.
Polybrominated biphenyls (PBB)	Not Detected	Draft IEC 62321. GC-MSD.
Polybrominated Diphenyl Ethers (PBDE)	Not Detected	Draft IEC 62321. GC-MSD.

Die Attach Paste

Substance	PPM	Method
Lead	Not Detected	Draft IEC 62321. ICP-OES.
Cadmium	Not Detected	Draft IEC 62321. ICP-OES.
Mercury	Not Detected	Draft IEC 62321. ICP-OES.
Chromium+6	Not Detected	Draft IEC 62321. UV-VIS.
Polybrominated biphenyls (PBB)	Not Detected	Draft IEC 62321. GC-MSD.
Polybrominated Diphenyl Ethers (PBDE)	Not Detected	Draft IEC 62321. GC-MSD.

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability tc
any inaccuracy of such information.

ANALOG DEVICES

Materials Declaration

Package	SOIC
Body Size	150 mils
LeadCount	16
Option	Sn/Pb

Molding Compound

Item	% of Compound	Weight (g)	PPM
Epoxy resin	10	1.04 E-02	63071
SiO2 Filler	85	8.88 E-02	536105
Phenol Resin	3	3.13 E-03	18921
Antimony_Sb2O3	1.5	1.57 E-03	9461
Brominated Resin	0.5	5.22 E-04	3154

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	97.5	5.57 E-02	336558
Fe	2.35	1.34 E-03	8112
P	0.03	1.71 E-05	104
Zn	0.12	6.86 E-05	414

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	4.45 E-04	2687

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	85	1.47 E-03	8.87 E+03
Pb	15	2.59 E-04	1.56 E+03

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	3.53 E-04	2131

Chip

	% of Chip	Weight (g)	PPM
Si	**100**	1.30 E-03	7831

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Resin	25	4.22 E-05	255
Ag Filler	75	1.27 E-04	765

Package Totals

Weight (g)	PPM
1.66 E-01	1000000

Molding Compound

Item	PPM	Method
Pb	<2	US EPA method #3052 & 6010E
Cd	Not Detected	BS EN 1122:2001 ICP AES
Hg	<2	US EPA method #3052 & 7471A
Cr+6	<2	US EPA method #3060A & 6010E

Die Attach Paste

Item	PPM	Method
Pb	<5	ICP AES
Cd	<5	ICP AES
Hg	<5	ICP AES
Cr+6	<5	ICP AES
PBB	Not Detected	
PBDE	Not Detected	

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ANALOG DEVICES